| | Material Composit © Copyright 2005. IPC, I nternational and Pan-Am | Bannockb | urn, Illinois. A | ll rights reserved u | inder both | This docume level parts, ti | ent is a decla he declaratio | aration on enco | of the subsompasses a | stances v 11 lower | vithin the level mate | manufactur erials for w | er listed i hich the n | tem. N nanufa | lote: if th cturer ha | e item is an as s engineering | sembly with low responsibility. |
|--|--|------------|---|----------------------|--------------------------------------|--------------------------------|---------------------------------|---|-----------------------|-----------------------|---------------------------------|---------------------------------|---------------------------|------------------|--------------------------|----------------------------------|------------------------------------|
| | | | | | Form Type ³ Distribute | | | | | | ous Materi | rials and Mfg Information | | | | | |
| Supplier Informati | ion | | | | | | | | | | | | | | | | |
| Company name* | | | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | | | | |
| onsemi | | | | | | | | | | | | 2024-05-21 | | | | | |
| Contact Name | | | Title - Contact | | |] | Phone - Contact* | | | | | Email - Contact* | | | | | |
| Product-Env-Stewards | | | Product Enviro Compliance | | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | | |
| Authorized Representative* | | | Title - Representative | | | Phone - Representative* | | | | | Email - Representative* | | | | | | |
| Product-Env-Stewards | | | Product Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | | | |
| Requester Ite | NCP718ASN330T1G 300 | | n Number Mfr Item Name | | | | Effective D | fective Date Version Manufacturing Site | | ing Site | | Weigh | ıt* | UOM | Unit Type | | |
| | | | 300 mA Low Iq, Wide Input Voltage LDO - TSOP5 3V3 AD | | | 2024-05-21 TH | | THB | | | 12.52 | | mg | Each | | | |
| /Ianufacturing Pro | occess Information | l | | | | | | | | | | | | | | | |
| Terminal Plat | Terminal Plating / Grid Array Material | | Ferminal Base Alloy J-ST | | J-STD-020 MSL | D-020 MSL Rating | | Peak Process Body Temperatu | | peratur | are Max Time at Peak Tem | | Temperat | ure | Number | of Reflow Cyc | les |
| Precious metal (e.g. Ag,Au, NiPdAu) (no Sn) | | l) (no C | CU Alloy 1 | | 1 | | 260 | | С | | 30 | | secon | ds . | 3 | | |
| Comments | | | | | | | | | | | | | | | | | |
| vel 1 - maximum time | e at peak temperature d | uring sol | dering is 10-3 | 0 seconds | | | | | | | | | | | | | |
| or more information 1 | regarding material com | position p | olease refer to | page 3 | | | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | |
|--|--|--|---|---|---|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | nium (Cr6+), Polybro | ominated Biphenyls (PBB), Polybron | dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | ances per the definitio | on above | Supplier Acceptance | * Accepted | | | | |
| Exemption: If the declared item does not con applicable exemptions. | ntain RoHS restricted substances per | the definition above | except for defined RoHS exempti | ons, then select the corresponding response i | n the RoHS Declaration above and choose all | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | |
| Declaration Signature | | | | | | | | | |
| Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester. | | | | | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|--------|-----------------|
| Die | 0.3 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.3 | mg |
| Die Attach Epoxy | 0.1 | mg | Supplier | Poly(oxypropylene)diamine | 9046-10-0 | | 0.003 | mg |
| | | | Supplier | Silver (Ag) | 7440-22-4 | | 0.085 | mg |
| | | | Supplier | Proprietary | Proprietary Data | | 0.005 | mg |
| | | | Supplier | Phenolic Resin (Novolac) | 9003-35-4 | | 0.007 | mg |
| Lead Frame | 6.43 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0077 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.1511 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 6.2692 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0019 | mg |
| Mold Compound-Black | 5.6 | mg | | Epoxy resin | proprietary data | | 0.28 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 0.112 | mg |
| | | | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 0.14 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.028 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 5.04 | mg |
| Plating | 0.07 | mg | Supplier | Palladium (Pd) | 7440-05-3 | | 0.0017 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 0.0616 | mg |
| | | | Supplier | Gold (Au) | 7440-57-5 | | 0.0067 | mg |
| Vire Bond - Cu | 0.02 | mg | Supplier | Palladium (Pd) | 7440-05-3 | | 0.0004 | mg |
| | | | Supplier | Gold (Au) | 7440-57-5 | | 0 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.0196 | mg |